

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

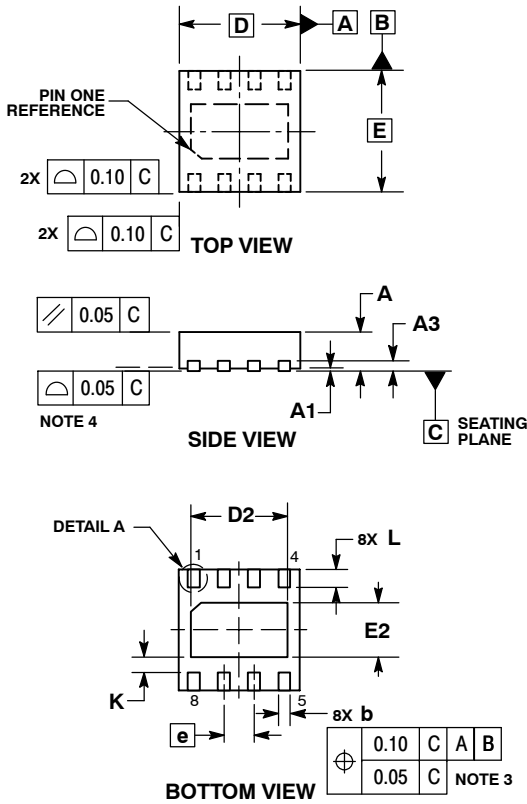
ON Semiconductor®



SCALE 2:1

CDFN8 2x2, 0.5P
CASE 505AG
ISSUE O

DATE 20 AUG 2012



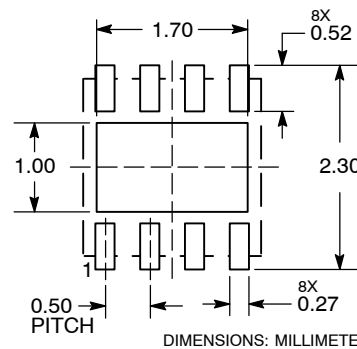
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.10 AND 0.20MM FROM THE TERMINAL TIP.
 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.60	0.70
A1	0.00	0.05
A3	0.20 REF	
b	0.15	0.25
D	2.00 BSC	
D1	1.80 BSC	
D2	1.45	1.70
E	2.00 BSC	
E2	0.75	1.00
e	0.50 BSC	
K	0.15	---
L	0.20	0.40

GENERIC MARKING DIAGRAM*

*No marking due to clear package

RECOMMENDED MOUNTING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	CDFN8, 2X2, 0.5P	PAGE 1 OF 2

